

SCDS230-APRIL 2006

#### **FEATURES**

- Specified Break-Before-Make Switching
- Low ON-State Resistance (0.75  $\Omega$  Max)
- Control Inputs Referenced to V<sub>IO</sub>
- Low Charge Injection
- Excellent ON-State Resistance Matching
- Low Total Harmonic Distortion (THD)
- 2.25-V to 5.5-V Power Supply (V<sub>1</sub>)
- 1.65-V to 1.95-V Logic Supply (V<sub>IO</sub>)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 4000-V Human-Body Model (A114-B, Class II)
  - 1000-V Charged-Device Model (C101)
  - 400-V Machine Model (A115-A)

- COM Port to GND
  - 8000-V Human-Body Model (A114-B, Class II)
  - ±15-kV Contact Discharge (IEC 61000-4-2)

#### **APPLICATIONS**

- Cell Phones
- PDAs
- Portable Instrumentation

YZT PACKAGE (BOTTOM VIEW)



### **DESCRIPTION/ORDERING INFORMATION**

The TS5A6542 is a single-pole double-throw (SPDT) analog switch that is designed to operate from 2.25 V to 5.5 V. The device offers a low ON-state resistance with an excellent channel-to-channel ON-state resistance matching, and the break-before-make feature to prevent signal distorion during the transferring of a signal from one path to another. The device has excellent total harmonic distortion (THD) performance and consumes very low power. These features make this device suitable for portable audio applications.

The TS5A6542 has a separate logic supply pin  $(V_{IO})$  operates from 1.65 V to 1.95 V.  $V_{IO}$  powers the control circuitry, which allows the TS5A6542 to be controlled by 1.8-V signals.

#### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING(2)
-40°C to 85°C	NanoFree <sup>™</sup> – WCSP (DSBGA) 0.23-mm Large Bump – YZT (Pb-free) 0.625-mm max height	Tape and reel	TS5A6542YZTR	JH7

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) YZT: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### SUMMARY OF CHARACTERISTICS(1)

Configuration	2:1 Multiplexer/Demultiplexer (1 × SPDT)
Number of channels	1
ON-state resistance (r <sub>on</sub> )	0.75 Ω max
ON-state resistance match (Δr <sub>on</sub> )	0.1 Ω max
ON-state resistance flatness [(r <sub>on(flat)</sub> ]	0.1 Ω max
Turn-on/turn-off time (t <sub>ON</sub> /t <sub>OFF</sub> )	25 ns/20 ns
Charge injection (Q <sub>C</sub> )	15 pC
Bandwidth (BW)	43 MHz
OFF isolation (O <sub>ISO</sub> )	-63 dB at 1 MHz
Crosstalk (X <sub>TALK</sub> )	-63 dB at 1 MHz
Total harmonic distortion (THD)	0.004%
Leakage current [I <sub>NO(OFF)</sub> /I <sub>NC(OFF)</sub> ]	20 nA
Package option	8-pin WCSP

(1)  $V_{+} = 5 \text{ V}, T_{A} = 25^{\circ}\text{C}$ 

#### **FUNCTION TABLE**

IN	NC TO COM, COM TO NC	NO TO COM, COM TO NO
L	ON	OFF
Н	OFF	ON

## Absolute Maximum Ratings (1)(2)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{+}$ $V_{IO}$	Supply voltage range <sup>(3)</sup>		-0.5	6.5	V
V <sub>NC</sub> V <sub>NO</sub> V <sub>COM</sub>	Analog voltage range (3)(4)(5)		-0.5	V <sub>+</sub> + 0.5	٧
I <sub>I/OK</sub>	Analog port diode current <sup>(6)</sup>	$V_{NO}$ , $V_{COM} < 0$ or $V_{NO}$ , $V_{COM} > V_{+}$	-50	50	mA
I <sub>NC</sub>	On-state switch current		-200	200	
I <sub>NO</sub> I <sub>COM</sub>	On-state peak switch current <sup>(7)</sup>	$V_{NO,} V_{COM} = 0 \text{ to } V_{+}$	-400	400	mA
VI	Digital input voltage range <sup>(3)(4)</sup>		-0.5	6.5	V
I <sub>IK</sub>	Digital input clamp current	V <sub>I</sub> < 0	-50		mA
I <sub>+</sub> I <sub>GND</sub>	Continuous current through V <sub>+</sub> or GND		-100	100	mA
$\theta_{JA}$	Package thermal impedance <sup>(8)</sup>			102	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum

(3) All voltages are with respect to ground, unless otherwise specified.

(5) This value is limited to 5.5 V maximum.

(7) Pulse at 1-ms duration <10% duty cycle

<sup>(4)</sup> The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>(6)</sup> Requires clamp diodes on analog port to V<sub>+</sub>

<sup>(8)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.



## Electrical Characteristics for 5-V Supply<sup>(1)</sup>

 $V_+ = 4.5 \text{ V}$  to 5.5 V,  $V_{IO} = 1.65 \text{ V}$  to 1.95 V,  $T_A = -40 ^{\circ}\text{C}$  to 85 °C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDIT	TIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT	
Analog Switch		1						'		
Analog signal range	${\sf V_{COM}}, {\sf V_{NO}}$					0		V <sub>+</sub>	V	
ON-state resistance	r <sub>on</sub>	$V_{NO}$ or $V_{NC}$ = 2.5 V, $I_{COM}$ = -100 mA,	Switch ON, See Figure 14	25°C Full	4.5 V		0.5	0.75	Ω	
ON-state resistance match between channels	$\Delta r_{\sf on}$	$V_{NO}$ or $V_{NC} = 2.5 \text{ V}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 14	25°C Full	4.5 V		0.05	0.1	Ω	
ON-state resistance		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 14	25°C			0.1			
flatness	r <sub>on(flat)</sub>	$V_{NO}$ or $V_{NC} = 1 \text{ V}$ , 1.5 V, 2.5 V, $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 14	25°C Full	4.5 V		0.1	0.1 0.25	Ω	
		V <sub>NO</sub> = 1 V, 4.5 V,		25°C	Q	-20	2	20		
NO, NC OFF leakage current	I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	$V_{COM} = 4.5 \text{ V}, 1 \text{ V}, \ V_{NC} = \text{Open}, \ \text{or} \ V_{NO} = 1 \text{ V}, 4.5 \text{ V}, \ V_{COM} = 4.5 \text{ V}, 1 \text{ V}, \ V_{NO} = \text{Open}, \ $	Switch OFF, See Figure 15	Full	5.5 V	-100		100	nA	
		V <sub>NO</sub> = 1 V, 4.5 V,	C	25°C		-20	2	20		
NC, NO ON leakage current	I <sub>NO(ON)</sub>	$V_{COM}$ , $V_{NC}$ = Open, or $V_{NC}$ = 1 V, 4.5 V, $V_{COM}$ , $V_{NO}$ = Open,	Switch ON, See Figure 16	Full	5.5 V	-200		200	nA	
		V <sub>COM</sub> = 1 V, 4.5 V,		25°C		-20	2	20		
COM ON leakage current	I <sub>COM(ON)</sub>	$V_{NO}$ and $V_{NC}$ = Open, or $V_{COM}$ = 1 V, 4.5 V, $V_{NO}$ or $V_{NC}$ = Open,	See Figure 16	Full	5.5 V	-200		200	nA	
Digital Control Input (	IN) <sup>(2)</sup>									
Input logic high	$V_{IH}$	V <sub>IO</sub> = 1.65 V to 1.95 V		Full		$\begin{array}{c} 0.65 \\ \times  V_{IO} \end{array}$		$V_{IO}$	V	
Input logic low	$V_{IL}$	V <sub>IO</sub> = 1.65 V to 1.95 V		Full		0		$\begin{array}{c} 0.35 \\ \times  V_{IO} \end{array}$	V	
Input leakage current	I <sub>IH</sub> , I <sub>IL</sub>	V <sub>I</sub> = V <sub>IO</sub> or 0		25°C Full	5.5 V	-2 -20		20	nA	
				i uli		20		20		

 <sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 (2) All unused digital inputs of the device must be held at V<sub>IO</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.





# Electrical Characteristics for 5-V Supply<sup>(1)</sup> (continued) $V_{+} = 4.5 \text{ V to } 5.5 \text{ V}, V_{IO} = 1.65 \text{ V to } 1.95 \text{ V}, T_{A} = -40^{\circ}\text{C} \text{ to } 85^{\circ}\text{C} \text{ (unless otherwise noted)}$

PARAMETER	SYMBOL	TEST CO	ONDITIONS	T <sub>A</sub>	V+	MIN	TYP	MAX	UNIT
Dynamic	•							·	
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_+,$ $R_1 = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 18	25°C Full	5 V 4.5 V	1	12.5	25 30	ns
Turn-off time	t <sub>OFF</sub>	$V_{COM} = V_+,$	C <sub>L</sub> = 35 pF,	25°C	5 V	1	9.5	20	ns
	OIT	$R_L = 50 \Omega$ ,	See Figure 18	Full	4.5 V			25	
Break-before-make time	t <sub>BBM</sub>	$\begin{aligned} &V_{NC} = V_{NO} = V_{+}/2, \\ &R_{L} = 50 \ \Omega, \end{aligned}$	C <sub>L</sub> = 35 pF, See Figure 19	25°C Full	5 V 4.5 V	1	5	10 12	ns
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C <sub>L</sub> = 1 nF, See Figure 23	25°C	5 V		15		pC
NO OFF capacitance	C <sub>NO(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 17	25°C	5 V		37		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 17	25°C	5 V		130		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 17	25°C	5 V		130		pF
Digital input capacitance	Cı	$V_I = V_{IO}$ or GND,	See Figure 17	25°C	5 V		6.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	5 V		43		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 1 MHz,	See Figure 21	25°C	5 V		-63		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , $f = 1 \text{ MHz}$ ,	See Figure 22	25°C	5 V		-63		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 \text{ pF},$	f = 20 Hz to 20 kHz, See Figure 24	25°C	5 V		0.004		%
Supply									
Positive supply current	I <sub>+</sub>	V <sub>I</sub> = V <sub>IO</sub> or GND		25°C Full	5.5 V		5.5	100 750	nA

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



SCDS230-APRIL 2006

## Electrical Characteristics for 3.3-V Supply<sup>(1)</sup>

 $V_{+} = 3 \text{ V}$  to 3.6 V,  $V_{IO} = 1.65 \text{ V}$  to 1.95 V,  $T_{A} = -40^{\circ}\text{C}$  to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDIT	TIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch					•	•			
Analog signal range	$V_{COM}$ , $V_{NO}$					0		V <sub>+</sub>	V
ON-state resistance	r <sub>on</sub>	$V_{NO}$ or $V_{NC} = 2 V$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 14	25°C Full	3 V		0.75	0.9	Ω
ON-state resistance match between channels	$\Delta r_{ m on}$	$V_{NO}$ or $V_{NC} = 2 \text{ V}$ , 0.8 V, $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 14	25°C Full	3 V		0.1	0.15 0.15	Ω
ON-state resistance		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -100 \text{ mA},$					0.2		
flatness	r <sub>on(flat)</sub>	$V_{NO}$ or $V_{NC} = 0.8 \text{ V}, 2 \text{ V}, $ $I_{COM} = -100 \text{ mA}, $	Switch ON, See Figure 14	25°C Full	3 V		0.1	0.3	Ω
		V <sub>NO</sub> = 1 V, 3 V, V <sub>COM</sub> = 3 V, 1 V,		25°C		-20	2	20	
NO, NC OFF leakage current	I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	$\begin{array}{l} V_{NC} = \text{Open,} \\ \text{or} \\ V_{NC} = 1 \text{ V, } 3 \text{ V,} \\ V_{COM} = 3 \text{V, } 1 \text{ V,} \\ V_{NO} = \text{Open,} \end{array}$	Switch OFF, See Figure 15	Full	3.6 V	-50		50	nA
NC, NO ON leakage current	I <sub>NO(ON)</sub>	$V_{NO}$ = 1 V, 3 V, $V_{NC}$ and $V_{COM}$ = Open, or $V_{NC}$ = 1 V, 3 V, $V_{NO}$ and $V_{COM}$ = Open,	Switch ON, See Figure 16	25°C Full	3.6 V	-10 -30	2	10 30	nA
COM ON leakage current	I <sub>COM(ON)</sub>	$\begin{aligned} &V_{COM} = 1 \text{ V,} \\ &V_{NO} \text{ and } V_{NC} = \text{Open,} \\ &\text{or} \\ &V_{COM} = 3 \text{ V,} \\ &V_{NO} \text{ and } V_{NC} = \text{Open,} \end{aligned}$	See Figure 16	25°C Full	3.6 V	-10 -30	2	30	nA
Digital Control Input (	IN) <sup>(2)</sup>								
Input logic high	V <sub>IH</sub>	V <sub>IO</sub> = 1.65 V to 1.95 V		Full		$\begin{array}{c} 0.65 \\ \times  V_{IO} \end{array}$		V <sub>IO</sub>	V
Input logic low	$V_{IL}$	V <sub>IO</sub> = 1.65 V to 1.95 V		Full		0		$\begin{array}{c} 0.35 \\ \times  V_{IO} \end{array}$	V
Input leakage current	$I_{\mathrm{lH}},I_{\mathrm{lL}}$	V <sub>I</sub> = V <sub>IO</sub> or 0		25°C Full	3.6 V	-2 -20		20	nA

 <sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 (2) All unused digital inputs of the device must be held at V<sub>IO</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCDS230-APRIL 2006

# Electrical Characteristics for 3.3-V Supply<sup>(1)</sup> (continued) $V_{+} = 3 \text{ V to } 3.6 \text{ V}, V_{IO} = 1.65 \text{ V to } 1.95 \text{ V}, T_{A} = -40^{\circ}\text{C to } 85^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	SYMBOL	TEST C	ONDITIONS	T <sub>A</sub>	V+	MIN	TYP	MAX	UNIT
Dynamic	•								
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_+,$ $R_1 = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 18	25°C Full	3.3 V 3 V	5	15	30 35	ns
		L ,		25°C	3.3 V	1	9	20	
Turn-off time	t <sub>OFF</sub>	$V_{COM} = V_+,$ $R_L = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 18	Full	3.3 V	1		25	ns
Break-before-make	t	$V_{NC} = V_{NO} = V_{+}/2,$	C <sub>L</sub> = 35 pF,	25°C	3.3 V	1	8	13	ns
time	t <sub>BBM</sub>	$R_L = 50 \Omega$ ,	See Figure 19	Full	3 V	1		15	115
Charge injection	Q <sub>C</sub>	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C <sub>L</sub> = 1 nF, See Figure 23	25°C	3.3V		6.5		рС
NO OFF capacitance	C <sub>NO(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 17	25°C	3.3 V		38		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 17	25°C	3.3 V		133		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 17	25°C	3.3 V		133		pF
Digital input capacitance	Cı	$V_I = V_{IO}$ or GND,	See Figure 17	25°C	3.3 V		6.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	3.3 V		42		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 1 MHz,	See Figure 21	25°C	3.3 V		-63		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , $f = 1 MHz$ ,	See Figure 22	25°C	3.3 V		-63		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 pF,$	f = 20 Hz to 20 kHz, See Figure 24	25°C	3.3 V		0.004		%
Supply								'	
Positive supply	. \	W W CND		25°C	2.6.1/		10	50	- 1
current	I <sub>+</sub>	$V_I = V_{IO}$ or GND		Full	3.6 V			300	nA

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



SCDS230-APRIL 2006

## Electrical Characteristics for 2.5-V Supply<sup>(1)</sup>

 $V_{+} = 2.25 \text{ V}$  to 2.75 V,  $V_{IO} = 1.65 \text{ V}$  to 1.95 V,  $T_{A} = -40 ^{\circ}\text{C}$  to 85  $^{\circ}\text{C}$  (unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDIT	TIONS	T <sub>A</sub>	V <sub>+</sub>	MIN	TYP	MAX	UNIT
Analog Switch						•			
Analog signal range	$V_{\rm COM}^{}, \ V_{\rm NO}^{}$					0		V <sub>+</sub>	V
ON-state resistance	r <sub>on</sub>	$V_{NO}$ or $V_{NC} = 1.8 \text{ V}$ , $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 14	25°C Full	2.25 V		1	1.3 1.6	Ω
ON-state resistance match between channels	$\Delta r_{\sf on}$	V <sub>NO</sub> or V <sub>NC</sub> = 1.8 V, 0.8 V, I <sub>COM</sub> = -100 mA,	Switch ON, See Figure 14	25°C Full	2.25 V		0.15	0.2	Ω
		$0 \le (V_{NO} \text{ or } V_{NC}) \le V_+,$ $I_{COM} = -100 \text{ mA},$	Switch ON, See Figure 14	25°C			0.5		
ON-state resistance flatness	r <sub>on(flat)</sub>	$V_{NO}$ or $V_{NC} = 0.8 \text{ V}$ , 1 V, 1.8 V, $I_{COM} = -100 \text{ mA}$ ,	Switch ON, See Figure 14	25°C Full	2.25 V		0.25	0.5	Ω
		V <sub>NO</sub> = 0.5 V, 2.2 V,		25°C		-20	2	20	
NO, NC OFF leakage current	I <sub>NO(OFF)</sub> , I <sub>NC(OFF)</sub>	$\begin{aligned} &V_{COM} = 2.2 \text{ V}, \ 0.5 \text{ V}, \\ &V_{NC} = \text{Open}, \\ &\text{or} \\ &V_{NC} = 0.5 \text{ V}, 2.2 \text{ V}, \\ &V_{COM} = 2.2 \text{ V}, 0.5 \text{ V}, \\ &V_{NO} = \text{Open}, \end{aligned}$	Switch OFF, See Figure 15	Full	2.75 V	-50		50	nA
NC, NO ON leakage current	I <sub>NO(ON)</sub>	$\begin{split} &V_{NO} = 0.5 \text{ V}, 2.2 \text{ V}, \\ &V_{NC} \text{ and } V_{COM} = \text{Open}, \\ &\text{or} \\ &V_{NC} = 2.2 \text{ V}, 0.5 \text{ V}, \\ &V_{NO} \text{ and } V_{COM} = \text{Open}, \end{split}$	Switch ON, See Figure 16	25°C Full	2.75 V	-10 -20	2	10 20	nA
COM ON leakage current	I <sub>COM(ON)</sub>	$\begin{aligned} &V_{COM} = 0.5 \text{ V}, \\ &V_{NO} \text{ and } V_{NC} = \text{Open}, \\ &\text{or} \\ &V_{COM} = 2.2 \text{ V}, \\ &V_{NO} \text{ and } V_{NC} = \text{Open}, \end{aligned}$	Switch ON, See Figure 16	25°C Full	2.75 V	-10 -20	2	10 20	nA
Digital Control Input (	(IN) <sup>(2)</sup>				1			'	
Input logic high	V <sub>IH</sub>	V <sub>IO</sub> = 1.65 V to 1.95 V		Full		$\begin{array}{c} 0.65 \\ \times  V_{IO} \end{array}$		V <sub>IO</sub>	V
Input logic low	$V_{IL}$	V <sub>IO</sub> = 1.65 V to 1.95 V		Full		0		$\begin{array}{c} 0.35 \\ \times  V_{IO} \end{array}$	V
Input leakage current	$I_{\rm IH},~I_{\rm IL}$	V <sub>I</sub> = V <sub>IO</sub> or 0		25°C Full	2.75 V	-2 -20		20	nA

The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum
 All unused digital inputs of the device must be held at V<sub>IO</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCDS230-APRIL 2006

# Electrical Characteristics for 2.5-V Supply<sup>(1)</sup> (continued) $V_{+} = 2.25 \text{ V}$ to 2.75 V, $V_{IO} = 1.65 \text{ V}$ to 1.95 V, $T_{A} = -40 ^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER	SYMBOL	TEST CO	ONDITIONS	T <sub>A</sub>	V+	MIN	TYP	MAX	UNIT
Dynamic									
Turn-on time	t <sub>ON</sub>	$V_{COM} = V_+,$ $R_1 = 50 \Omega,$	C <sub>L</sub> = 35 pF, See Figure 18	25°C Full	2.5 V 2.25 V	5 5	20	35 40	ns
	_	$V_{COM} = V_+,$	$C_1 = 35 \text{ pF},$	25°C	2.5 V	2	10	20	
Turn-off time	t <sub>OFF</sub>	$R_L = 50 \Omega$	See Figure 18	Full	2.25 V	2		25	ns
Break-before-make	t <sub>BBM</sub>	$V_{NC} = V_{NO} = V_{+}/2,$	C <sub>L</sub> = 35 pF,	25°C	2.5 V	1	11	20	ns
time	BBIVI	$R_L = 50 \Omega$ ,	See Figure 19	Full	2.25 V	1		25	
Charge injection	$Q_C$	$V_{GEN} = 0,$ $R_{GEN} = 0,$	C <sub>L</sub> = 1 nF, See Figure 23	25°C	2.5 V		5		pC
NO OFF capacitance	C <sub>NO(OFF)</sub>	V <sub>NO</sub> = V <sub>+</sub> or GND, Switch OFF,	See Figure 17	25°C	2.5 V		38		pF
NC, NO ON capacitance	C <sub>NC(ON)</sub> , C <sub>NO(ON)</sub>	V <sub>NC</sub> or V <sub>NO</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 17	25°C	2.5 V		135		pF
COM ON capacitance	C <sub>COM(ON)</sub>	V <sub>COM</sub> = V <sub>+</sub> or GND, Switch ON,	See Figure 17	25°C	2.5 V		135		pF
Digital input capacitance	C <sub>I</sub>	$V_I = V_{IO}$ or GND,	See Figure 17	25°C	2.5 V		6.5		pF
Bandwidth	BW	$R_L = 50 \Omega$ , Switch ON,	See Figure 20	25°C	2.5 V		40		MHz
OFF isolation	O <sub>ISO</sub>	$R_L = 50 \Omega$ , f = 1 MHz,	See Figure 21	25°C	2.5 V		-63		dB
Crosstalk	X <sub>TALK</sub>	$R_L = 50 \Omega$ , $f = 1 \text{ MHz}$ ,	See Figure 22	25°C	2.5 V		-63		dB
Total harmonic distortion	THD	$R_L = 600 \Omega,$ $C_L = 50 \text{ pF},$	f = 20 Hz to 20 kHz, See Figure 24	25°C	2.5 V		0.008		%
Supply									
Positive supply	I <sub>+</sub>	$V_I = V_{IO}$ or GND		25°C	2.75 V		10	25	nA
current	'+	VI - VIO OI OIVD		Full	2.10 V			100	ПА

<sup>(1)</sup> The algebraic convention, whereby the most negative value is a minimum and the most positive value is a maximum



#### **TYPICAL PERFORMANCE**

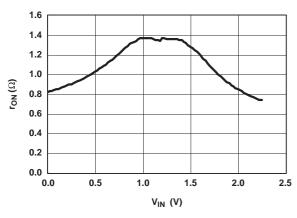


Figure 1.  $r_{on}$  vs  $V_{COM}$  ( $V_{+} = 2.5 \text{ V}$ )

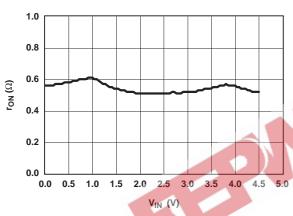


Figure 3.  $r_{on}$  vs  $V_{COM}$  ( $V_{+} = 5$  V)

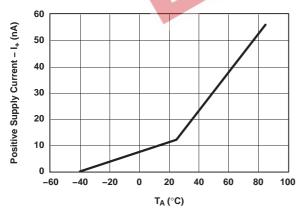


Figure 5.  $I_+$  vs Temperature ( $V_+$  = 5 V)

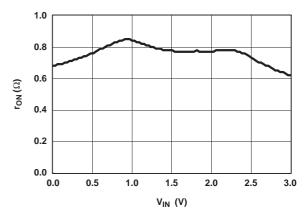


Figure 2.  $r_{on}$  vs  $V_{COM}$  ( $V_{+} = 3.3 \text{ V}$ )

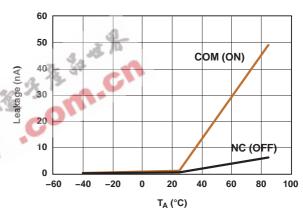


Figure 4. Leakage Current vs Temperature ( $V_{+} = 5 \text{ V}$ )

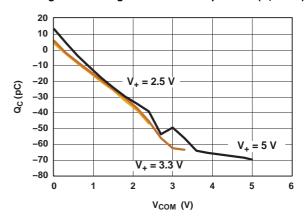
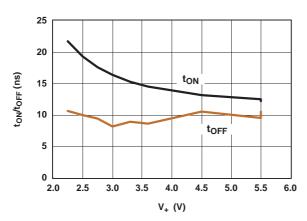


Figure 6. Charge Injection (Q<sub>C</sub>) vs V<sub>COM</sub>



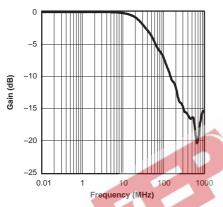
## **TYPICAL PERFORMANCE (continued)**



14 toN tow/toff (ns) 12 toff 10 8 -40 -20 0 20 40 60 80 100 -60 T<sub>A</sub> – Temperature °C

Figure 7.  $t_{\rm ON}/t_{\rm OFF}$  vs Supply Voltage

Figure 8.  $t_{ON}/t_{OFF}$  vs Temperature (V<sub>+</sub> = 5 V)



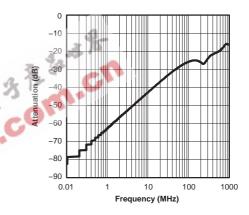
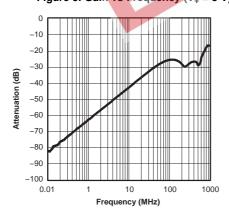


Figure 9. Gain vs Frequency  $(V_{+} = 5 \text{ V})$ 

Figure 10. Crosstalk vs Frequency  $(V_+ = 5 V)$ 



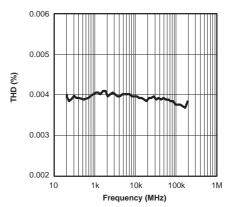


Figure 11. OFF Isolation vs Frequency ( $V_{+} = 5 \text{ V}$ )

Figure 12. Total Harmonic Distortion vs Frequency  $(V_+ = 2.5 \text{ V})$ 



### **TYPICAL PERFORMANCE (continued)**

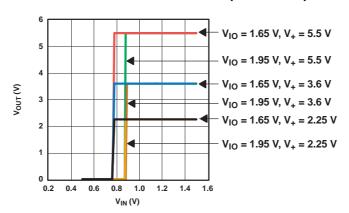


Figure 13. V<sub>IO</sub> Thresholds





#### PARAMETER MEASUREMENT INFORMATION

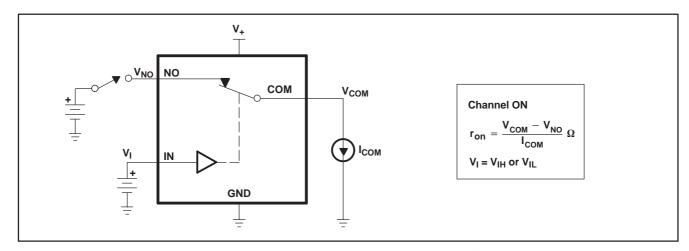


Figure 14. ON-State Resistance (ron)

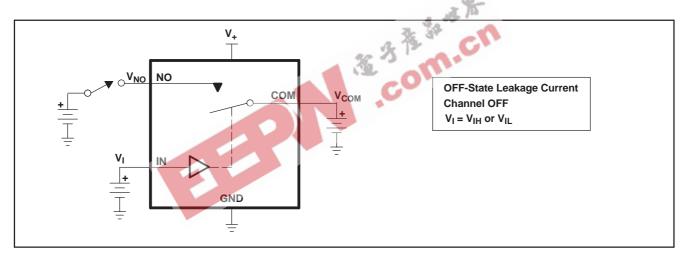


Figure 15. OFF-State Leakage Current ( $I_{COM(OFF)}$ ,  $I_{NC(OFF)}$ ,  $I_{COM(PWROFF)}$ ,  $I_{NC(PWR(FF))}$ )

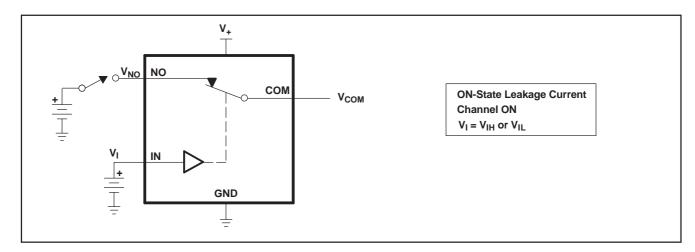


Figure 16. ON-State Leakage Current ( $I_{COM(ON)}$ ,  $I_{NC(ON)}$ )



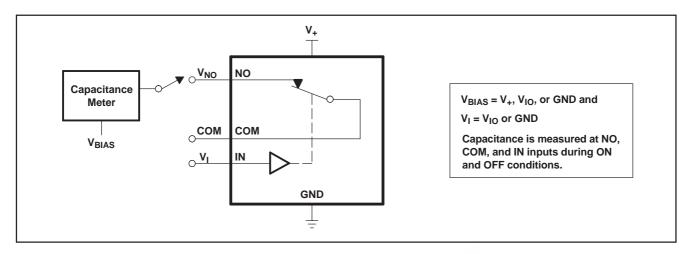
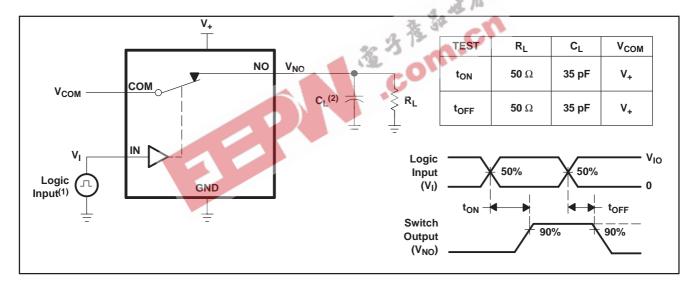


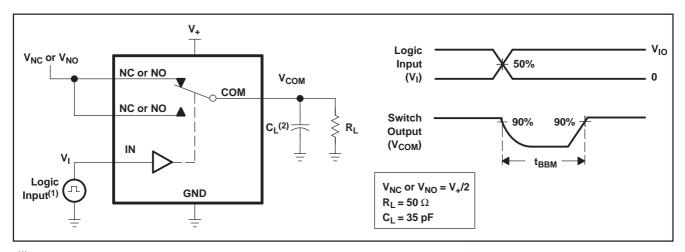
Figure 17. Capacitance (C<sub>I</sub>,  $C_{COM(OFF)}$ ,  $C_{COM(ON)}$ ,  $C_{NC(OFF)}$ ,  $C_{NC(ON)}$ )



- (1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_r < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .
- (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 18. Turn-On (t<sub>ON</sub>) and Turn-Off Time (t<sub>OFF</sub>)





- (1) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f$  < 5 ns.  $t_f$  < 5 ns.
- (2) C<sub>L</sub> includes probe and jig capacitance.

Figure 19. Break-Before-Make Time (t<sub>BBM</sub>)

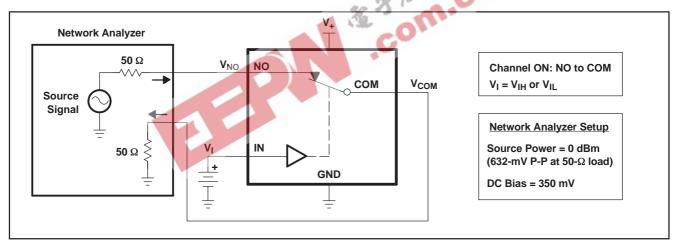


Figure 20. Bandwidth (BW)



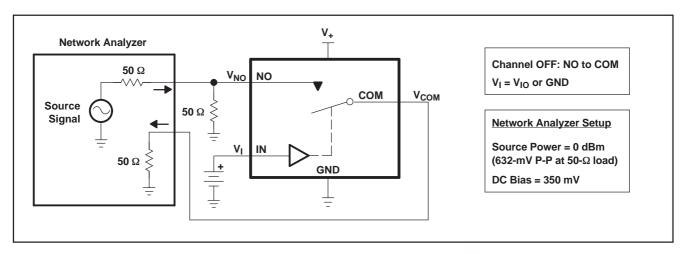


Figure 21. OFF Isolation (O<sub>ISO</sub>)

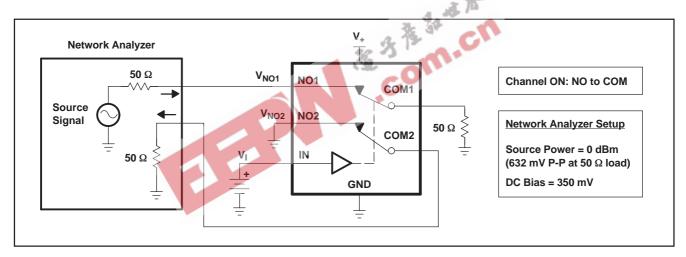
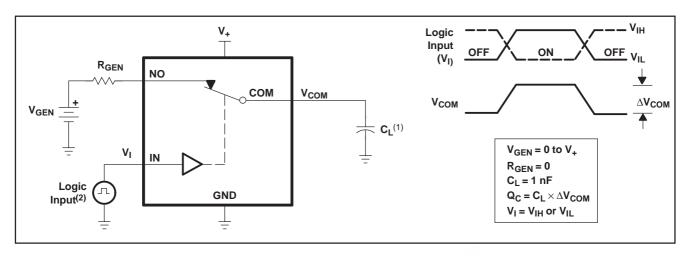


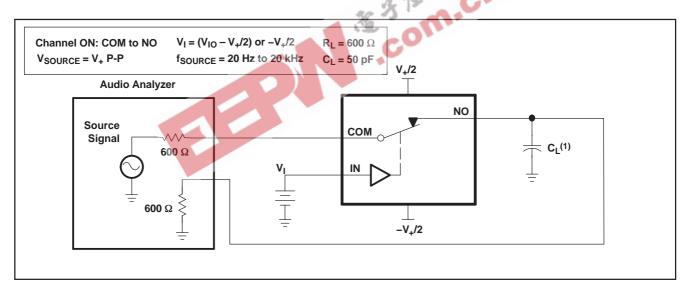
Figure 22. Crosstalk (X<sub>TALK</sub>)





- $^{(1)}\,$   $C_L$  includes probe and jig capacitance.
- (2) All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_f < 5 \text{ ns}$ ,  $t_f < 5 \text{ ns}$ .

Figure 23. Charge Injection (Qc)



 $^{(1)}$   $C_L$  includes probe and jig capacitance.

Figure 24. Total Harmonic Distortion (THD)



#### PACKAGE OPTION ADDENDUM

27-Jul-2006

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins Pa	ackage Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp (3)
TS5A6542YZPR	ACTIVE	WCSP	YZP	8	3000	Green (RoHS &	SNAGCU	Level-1-260C-UNLIM
						no Sb/Br)		

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <a href="http://www.ti.com/productcontent">http://www.ti.com/productcontent</a> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

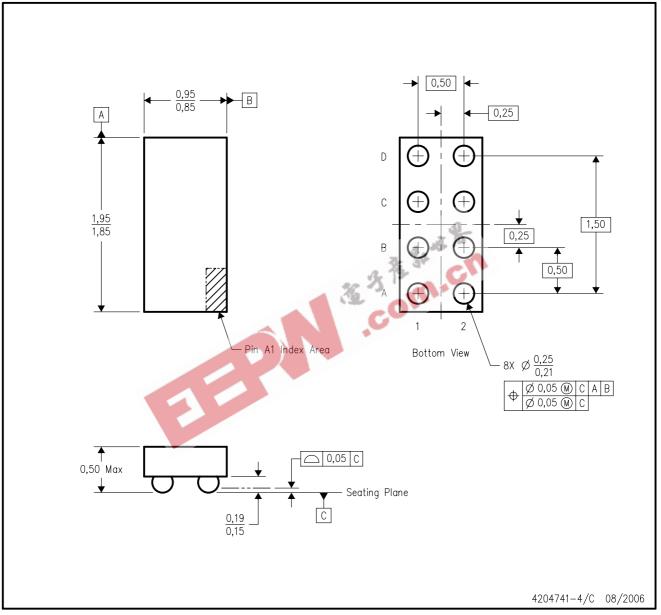
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## YZP (R-XBGA-N8)

## DIE-SIZE BALL GRID ARRAY



NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- B. This drawing is subject to change without notice.
   C. NanoFree™ package configuration.
- D. This package is lead-free. Refer to the 8 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.



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